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Product Change Notification - KSRA-28DZLH982

Date: 16 Feb 2018

Product Capacitive Touch Sensors; USB Bridge; 8-bit PIC

Category: Microcontrollers; 16-Bit - Microcontrollers and Digital Signal Controllers

Notification subject: CCB 2895 Final Notice:Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 200K wafer technology available in 20L QFN package at NSEB assembly site

Notification text: **PCN Status:**
Final notification.

PCN Type:
Manufacturing Change

Microchip Parts Affected:
Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:
Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 200K wafer technology available in 20L QFN package at NSEB assembly site.

Pre Change:
Assembled using gold (Au) bond wire, 8200T or 8600 die

attach material and G770HCD or G700LTD molding compound material

Post Change:

Assembled using palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach material, G700LTD molding compound material

Pre and Post Change Summary:

	Pre Change		Post Change
Assembly Site	UTAC Thai Limited LTD. (NSEB)		UTAC Thai Limited LTD. (NSEB)
Wire material	Au		CuPdAu
Die attach material	8200T	8600	8600
Molding compound material	G770HCD	G700LTD	G700LTD
Lead frame material	EFTEC-64T		EFTEC-64T

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity by qualifying palladium coated copper with gold flash (CuPdAu) bond wire at NSEB assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

March 16, 2018 (date code: 1811)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts

Time Table Summary:

	April 2017					-->	February 2018				March 2018				
	Workweek	13	14	15	16		17	05	06	07	08	09	10	11	12
Initial PCN Issue Date		X													
Qual Report Availability									X						
Final PCN Issue Date									X						
Estimated Implementation Date												X			

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report

Revision History:

April 05, 2017: Issued initial notification.

February 16, 2018: Issued final notification. Attached the Qualification Report. Revised the affected parts list. Provided estimated first ship date on March 16, 2018.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s): [PCN_KSRA-28DZLH982_Affected CPN.pdf](#)
[PCN_KSRA-28DZLH982_Qual Report.pdf](#)
[PCN_KSRA-28DZLH982_Affected CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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PCN_KSRA-28DZLH982 -CCB 2895 Final Notice: Qualification of CuPdAu bond wire in selected products of the 200K wafer technology available in 20L QFN package at NSEB assembly site.

Affected Catalog Part Numbers (CPN)

PCN_KSRA-28DZLH982
CATALOG_PART_NBR
A010201-I/MQ
A010201T-I/MQ
AR1100-I/MQ
AR1100T-I/MQ
MCP2200-E/MQ046
MCP2200-I/MQ
MCP2200-I/MQ031
MCP2200-I/MQ046
MCP2200-I/MQRVB
MCP2200T-E/MQ046
MCP2200T-I/MQ
MCP2200T-I/MQ031
MCP2200T-I/MQ046
MCP2200T-I/MQRVB
MCP2210-I/MQ
MCP2210T-I/MQ
PIC16F1459-E/ML
PIC16F1459-I/ML
PIC16F1459-I/MLC01
PIC16F1459T-I/ML
PIC16F1459T-I/ML020
PIC16F1459T-I/MLC01
PIC16F1507-E/ML
PIC16F1507-I/ML
PIC16F1507T-E/ML
PIC16F1507T-I/ML
PIC16F1508-E/ML
PIC16F1508-I/ML
PIC16F1508T-E/ML
PIC16F1508T-E/ML025
PIC16F1508T-I/ML
PIC16F1508T-I/MLOPP
PIC16F1509-E/ML
PIC16F1509-I/ML
PIC16F1509-I/ML045
PIC16F1509T-E/ML
PIC16F1509T-I/ML
PIC16F1509T-I/ML045
PIC16F1618-E/ML
PIC16F1618-I/ML
PIC16F1618T-I/ML
PIC16F1619-E/ML
PIC16F1619-I/ML

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Affected Catalog Part Numbers (CPN)

PCN_KSRA-28DZLH982
CATALOG_PART_NBR
PIC16F1619T-I/ML
PIC16F1707-E/ML
PIC16F1707-I/ML
PIC16F1707T-I/ML
PIC16F1708-E/ML
PIC16F1708-E/ML028
PIC16F1708-I/ML
PIC16F1708T-E/ML
PIC16F1708T-E/ML025
PIC16F1708T-E/ML026
PIC16F1708T-E/ML027
PIC16F1708T-E/ML028
PIC16F1708T-E/ML030
PIC16F1708T-I/ML
PIC16F1709-E/ML
PIC16F1709-I/ML
PIC16F1709-I/ML020
PIC16F1709T-E/ML
PIC16F1709T-I/ML
PIC16F1709T-I/ML020
PIC16F1768-E/ML
PIC16F1768-I/ML
PIC16F1768T-E/ML
PIC16F1768T-I/ML
PIC16F1769-E/ML
PIC16F1769-I/ML
PIC16F1769T-E/ML
PIC16F1769T-I/ML
PIC16F1828-E/ML
PIC16F1828-E/MLC02
PIC16F1828-I/ML
PIC16F1828-I/MLC04
PIC16F1828T-E/ML
PIC16F1828T-I/ML
PIC16F1829-E/ML
PIC16F1829-H/ML
PIC16F1829-I/ML
PIC16F1829-I/ML030
PIC16F1829-I/ML031
PIC16F1829T-E/ML
PIC16F1829T-H/ML
PIC16F1829T-I/ML
PIC16F1829T-I/ML030

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Affected Catalog Part Numbers (CPN)

PCN_KSRA-28DZLH982
CATALOG_PART_NBR
PIC16F1829T-I/ML031
PIC16F720-E/ML
PIC16F720-I/ML
PIC16F720T-I/ML
PIC16F721-E/ML
PIC16F721-I/ML
PIC16F721T-E/ML
PIC16F721T-I/ML
PIC16LF1459-E/ML
PIC16LF1459-I/ML
PIC16LF1459-I/MLC01
PIC16LF1459-I/MLC02
PIC16LF1459-I/MLC03
PIC16LF1459T-I/ML
PIC16LF1459T-I/MLC01
PIC16LF1459T-I/MLC02
PIC16LF1459T-I/MLC03
PIC16LF1507-E/ML
PIC16LF1507-I/ML
PIC16LF1507T-I/ML
PIC16LF1508-E/ML
PIC16LF1508-I/ML
PIC16LF1508T-I/ML
PIC16LF1509-E/ML
PIC16LF1509-I/ML
PIC16LF1509T-I/ML
PIC16LF1559-E/ML
PIC16LF1559-I/ML
PIC16LF1559T-I/ML
PIC16LF1618-E/ML
PIC16LF1618-I/ML
PIC16LF1618T-I/ML
PIC16LF1619-E/ML
PIC16LF1619-I/ML
PIC16LF1619T-I/ML
PIC16LF1707-E/ML
PIC16LF1707-I/ML
PIC16LF1707T-I/ML
PIC16LF1708-E/ML
PIC16LF1708-I/ML
PIC16LF1708T-I/ML
PIC16LF1709-E/ML
PIC16LF1709-I/ML

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PCN_KSRA-28DZLH982
CATALOG_PART_NBR
PIC16LF1709T-I/ML
PIC16LF1768-E/ML
PIC16LF1768-I/ML
PIC16LF1768T-I/ML
PIC16LF1769-E/ML
PIC16LF1769-I/ML
PIC16LF1769T-I/ML
PIC16LF1828-E/ML
PIC16LF1828-I/ML
PIC16LF1828T-I/ML
PIC16LF1828T-I/ML025
PIC16LF1829-E/ML
PIC16LF1829-I/ML
PIC16LF1829T-I/ML
PIC16LF720-E/ML
PIC16LF720-I/ML
PIC16LF720T-I/ML
PIC16LF721-E/ML
PIC16LF721-I/ML
PIC16LF721T-I/ML
PIC16LF721T-I/ML022
PIC16LF721T-I/ML024
PIC16LF721T-I/ML025
PIC16LF721T-I/ML028
PIC16LF721T-I/ML030
PIC18F13K22-E/ML
PIC18F13K22-E/MLC01
PIC18F13K22-I/ML
PIC18F13K22T-I/ML
PIC18F13K22T-I/ML020
PIC18F13K50-I/MQ
PIC18F13K50T-I/MQ
PIC18F14K22-E/ML
PIC18F14K22-I/ML
PIC18F14K22T-E/ML
PIC18F14K22T-I/ML
PIC18F14K50-E/MQ
PIC18F14K50-I/MQ
PIC18F14K50-I/MQ048
PIC18F14K50T-I/MQ
PIC18F14K50T-I/MQ029
PIC18F14K50T-I/MQ039
PIC18F14K50T-I/MQ044

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Affected Catalog Part Numbers (CPN)

PCN_KSRA-28DZLH982
CATALOG_PART_NBR
PIC18F14K50T-I/MQ045
PIC18F14K50T-I/MQ047
PIC18F14K50T-I/MQ048
PIC18LF13K22-E/ML
PIC18LF13K22-I/ML
PIC18LF13K22-I/ML023
PIC18LF13K22T-I/ML
PIC18LF13K22T-I/ML023
PIC18LF13K22T-I/ML024
PIC18LF13K50-I/MQ
PIC18LF13K50T-I/MQ
PIC18LF14K22-E/ML
PIC18LF14K22-I/ML
PIC18LF14K22T-E/ML
PIC18LF14K22T-E/ML021
PIC18LF14K22T-I/ML
PIC18LF14K50-I/MQ
PIC18LF14K50T-I/MQ
PIC24F04KA201-I/MQ
PIC24F04KA201T-I/MQ
PIC24F04KL101-E/MQ
PIC24F04KL101-I/MQ
PIC24F04KL101T-I/MQ
PIC24F08KA101-E/MQ
PIC24F08KA101-I/MQ
PIC24F08KA101T-E/MQ
PIC24F08KA101T-I/MQ
PIC24F08KA101T-I/MQC02
PIC24F08KL201-E/MQ
PIC24F08KL201-I/MQ
PIC24F08KL201T-I/MQ
PIC24F08KL301-E/MQ
PIC24F08KL301-I/MQ
PIC24F08KL301T-I/MQ
PIC24F08KL301T-I/MQ020
PIC24F08KL401-E/MQ
PIC24F08KL401-I/MQ
PIC24F16KA101-E/MQ
PIC24F16KA101-I/MQ
PIC24F16KA101T-E/MQ
PIC24F16KA101T-I/MQ
PIC24F16KL401-E/MQ
PIC24F16KL401-I/MQ

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Affected Catalog Part Numbers (CPN)

PCN_KSRA-28DZLH982
CATALOG_PART_NBR
PIC24F16KL401T-I/MQ